

23 April 2003

09/825,648

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|--|---|---------------------|
| 1 | 6 | (("6017437") or ("6183611") or ("6241825")).PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/23 12:26 |
| 2 | 17 | ("3826558" "4086870" "5000827" "5024746" "5095848" "5256274" "5368711" "5429733" "5437777" "5441629" "5447615" "5516414" "5830805" "5853559" "5885353" "5891251" "6019164").PN. | USPAT | 2003/04/23 11:56 |
| 3 | 2473 | 205/118,122,123,125,295,640.ccls. or 204/297.01,297.06,297.07,297.1.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/23 12:27 |
| 4 | 2 | (205/118,122,123,125,295,640.ccls. or 204/297.01,297.06,297.07,297.1.ccls.) and ((chuck or (wafer adj support) or platen or platform) near (adjustable or compliant or resilient or deformable or tilttable)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/23 12:31 |
| 5 | 7 | (205/118,122,123,125,295,640.ccls. or 204/297.01,297.06,297.07,297.1.ccls.) and ((chuck or (wafer adj support) or platen or platform or support) near (adjustable or compliant or resilient or deformable or tilttable)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/23 12:36 |
| 6 | 686 | (205/118,122,123,125,295,640.ccls. or 204/297.01,297.06,297.07,297.1.ccls.) and (wafer or microelectronic or semiconductor) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/23 12:40 |
| 7 | 11 | ((205/118,122,123,125,295,640.ccls. or 204/297.01,297.06,297.07,297.1.ccls.) and (wafer or microelectronic or semiconductor)) and ((chuck or (wafer adj support) or platen or platform or support) with (adjustable or compliant or resilient or deformable or tilttable)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/23 12:33 |
| 8 | 8 | (205/118,122,123,125,295,640.ccls. or 204/297.01,297.06,297.07,297.1.ccls.) and ((chuck or (wafer adj support) or platen or platform or support) near (adjustable or compliant or resilient or deformable or tilttable or conformable or conforming)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/23 12:39 |
| 9 | 58692 | 204/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/23 12:39 |
| 10 | 70 | 204/\$.ccls. and ((chuck or (wafer adj support) or platen or platform or support) near (adjustable or compliant or resilient or deformable or tilttable or conformable or conforming)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/23 12:40 |
| 11 | 10 | (204/\$.ccls. and ((chuck or (wafer adj support) or platen or platform or support) near (adjustable or compliant or resilient or deformable or tilttable or conformable or conforming))) and (wafer or microelectronic or semiconductor) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/23 12:40 |

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|----|---|---------------|-------|---------------------|
| 18 | 7 | 6019164.URPN. | USPAT | 2003/04/23 12:45 |
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